

EV Group and Notion Systems Team Up on Nanoimprint Lithography – April 19, 2023

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### Proven SiPaste® for Ultrafine Printing

Boost SPI yields with SiPaste® C201HF. Formulated for fine feature printing, it combines superior non-wet open performance with excellent stencil print transfer efficiency.  
**Indium Corporation**



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April 19, 2023

### EU Takes on US and Asia with Chip Subsidy Plan

The European Union agreed to a €43 billion (US\$47 billion) plan for its semiconductor industry in an attempt to catch up with the United States and Asia and start a green industrial revolution. The EU Chips Act, proposed by the European Commission last year and confirmed by Internal Market Commissioner Thierry Breton, aims to double the bloc's share of global chip output to 20% by 2030 and follows ...

**South China Morning Post**



### Ultrasonic/Thermosonic Bonding Paper

Ultrasonic power is introduced during thermocompression bonding to perform die bonding at low temperature & pressure. Paper identifies processes to improve thermosonic bonding. Read more.



**TRESKY Automation**

### Designing for Mil-Aero?

We know how to meet the stringent quality and testing standards for your mil-aero packaging and assembly solutions, from quick-turn prototypes to full production quantities.



**QP Technologies**

### Global Semiconductor Equipment Billings Reach Industry Record \$107.6 Billion in 2022

Worldwide sales of semiconductor manufacturing equipment increased 5% from \$102.6 billion in 2021 to an all-time record of \$107.6 billion last year, SEMI, the industry ...

**SEMI**

### The Great Debate: Ball Bonding vs Wedge Bonding

Over the years, microelectronic wire bond process and packaging engineers have debated whether to use ball or wedge bond technologies. This article will focus on the ...

**Technical Paper**

### SIA Applauds House Introduction of Bipartisan Legislation to Restore Immediate Deductibility of R&D Investments

The Semiconductor Industry Association (SIA) released the following statement from SIA President and CEO John Neuffer commending the introduction in the House of ...

**Semiconductor Industry Association**

## Technical Papers

- [Defluxing of Copper Pillar Bumped Flip-Chips](#)
- [Functional testing of 0.3mm pitch WLP](#)
- [Vacuum Fluxless Reflow Technology for Fine Pitch Interconnect Bumping Applications](#)
- [Master Advanced Packaging Inspection](#)
- [Optimized Reflow Solder TIMs Processes for Heterogeneous Packages](#)
- [Packaging Solutions for Unique Markets](#)
- [Keys to Component Lead Tinning Success](#)

### Do thin wafers have you frazzled?

Our new ADJUST-A-VAC allows you to reduce the vacuum pressure from just below atmospheric pressure to up to ten inches of mercury. A LED bar display shows the vacuum level.



**Virtual Industries, Inc.**

### Micro Components Engineered for EVs

We specialize in precision micro components that enables conductivity, reliability & efficient thermal management in power supply AC/DC DC/AC, battery system, MOSFET & IGBT.



**COINING**

### [Speakers at AICS Go In Depth on Green AI Computing](#)

The theme of the 5th IBM IEEE AI Compute Symposium (AICS), held at an IBM research center last fall in New York, was "scalability to sustainability." Symposium presenters ...

**EE Times**

### [Has Our Industry Become More Sustainable?](#)

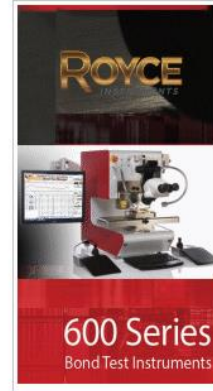
The quick answer to the question; "Is the semiconductor industry becoming more sustainable?" is "yes and no." There is undoubtedly more talk about sustainability and ...

**3DInCites**

### [Powerchip expects revenue to fall 5%](#)

Powerchip Semiconductor Manufacturing Corp expects revenue to decline up to 5% sequentially this quarter, extending a downtrend from the past three quarters as ...

**Taipei Times**



### [Cerebras's Open-Source GPT Models Trained at Wafer Scale](#)

Cerebras has open-sourced seven trained GPT-class large language models (LLMs), ranging in size from 111 million to 13 billion parameters, for use in research or commercial ...

**EE Times**

### [Tech war: China's chip output shows recovery in March amid US export restrictions on advanced tools](#)

The latest economic data published by China's statistics bureau points to a recovery in the national semiconductor industry, despite intensifying efforts by Washington to ...

**South China Morning Post**

### [Semiconductor chip – Can India chip in?](#)

The semiconductor chip industry started with the invention of the transistor in 1947 by Bell Labs. Almost 80 years later, this tiny technological marvel has become indispensable ...

**The Times of India**

**IC Device & Micro-Electronic Cleaning**  
Answering the needs of packaging engineers, Kyzen offers modern cleaning chemistry proven effective for all IC devices & micro-electronics. Cost effective cleaning is no longer a challenge.  
**Kyzen Corporation**



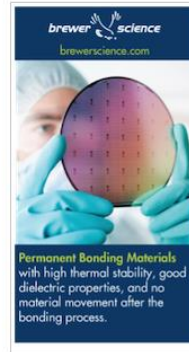
**Keys to Reliable Tin Mitigation**  
A more reliable method to mitigate tin whiskers is the robotic hot solder dip processing of components before assembly. This white paper identifies the key process considerations. Read more.  
**Circuit Technology Center**



### [Research Bits: April 18](#)

Researchers from Peking University developed a new chip-sized microwave photonic filter to separate communication signals from noise and suppress unwanted interference ...

**Semiconductor Engineering**




**Calendar**

- [Apr 23, 2023: Overview of semiconductor manufacturing Webinar for American Attendees](#)
- [Apr 25, 2023: Components for Military & Space Electronics Conference](#)
- [Apr 25, 2023: Intro to semiconductor design and fabrication/ Chandler, AZ](#)
- [Apr 26, 2023: Overview of Semiconductor Manufacturing/Chandler, AZ](#)

**IC Device & Micro-Electronic Cleaning**  
 Answering the needs of packaging engineers, Kyzen offers modern cleaning chemistry proven effective for all IC devices & micro-electronics. Cost effective cleaning is no longer a challenge.  
**Kyzen Corporation**



**Keys to Reliable Tin Mitigation**  
 A more reliable method to mitigate tin whiskers is the robotic hot solder dip processing of components before assembly. This white paper identifies the key process considerations. Read more.  
**Circuit Technology Center**




**Test Your Knowledge**

Lexicology is the study of what?  
 See answer below.

**A Lifespan of Reliability**  
 Nordson Electronics Solutions makes reliable electronics an everyday reality. Selective soldering, dispensing, coating, and plasma solutions.  
**Nordson Electronics Solutions**



**IDG Hosts Commercial Fab Facilities CHIPS-NOFO Meeting at NeoCity**  
 As Florida strengthens its role in providing microelectronics to support the nation's domestic supply chain, Osceola County, Florida welcomed partners throughout the state ...  
**BRIDG**

**Press Releases**  
**[EV Group and Notion Systems Team Up on Nanoimprint Lithography](#)**  
 EV Group (EVG) announced that they have entered into an agreement to develop the first fully integrated and automated nanoimprint lithography (NIL) solution with inkjet ...  
**EV Group**

**SAWA SC-BM500E Automatic Stencil Cleaner**  
 Ultrasonic combined with spray cleaning provides an excellent solution for all kinds of applications including wafer bump and electroform stencils.  
**Seika**



**StratEdge Pushes High-Temperature Packaging Technology to the Extreme at Upcoming Events**  
 StratEdge Corporation is set to showcase its latest packaging technology for high-temperature applications at several industry conferences in April and May. The events ...  
**StratEdge Corporation**

**Quote of the Day**  
 "If an elderly but distinguished scientist says that something is possible, he is almost certainly right; but if he says that it is impossible, he is very probably wrong."  
**Arthur C. Clarke**

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Ensure Top-Quality IC Performance with Our Reliable Assembly and Qualification Testing Services. Contact Us Today!

**Golden Altos Corporation**



#### Temporary Bonder & Debonder

Wafer support system (i) conventional process and (ii) hybrid dual bonding process executed in vacuum and applicable to, 3D IC, FOWLP, and power devices.

**Sciencetech Corporation**



#### Epoxy for Glob Top & Chip Coating

Master Bond Supreme 3CCM-85 is a non-premixed and frozen, one component epoxy formulated to cure at the lower temperature of 85°C.

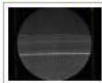
**Master Bond**



#### New Packaging FA Solutions Using Correlated X-ray Microscopy, LaserFIB

New advances using LaserFIB and 3D X-ray microscopy enable targeted cross-section preparation and analysis of defects in less than five hours. Read more.

**ZEISS Microscopy**



#### Cartoon of the Day



"What do we make where I work? We make excuses."

Copyright © Randy Glasbergen

#### What Year Was It?

##### First Boston Marathon

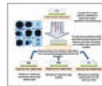
John J. McDermott of New York won the first Boston Marathon with a time of 2:55:10.

**The day was Apr 19. What year was it?**



#### Dicing Die-Attach Film (DDAF) or Dicing Die-Attach Tape (DDAT)

AI Technology pioneered the use of flexible die-attach film and paste adhesives for larger chip and die bonding. We now have extended our adhesive line. See more **A.I. Technology, Inc.**



#### Test Your Knowledge Answer

Lexicology is the study of what?

Answer: Words

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